

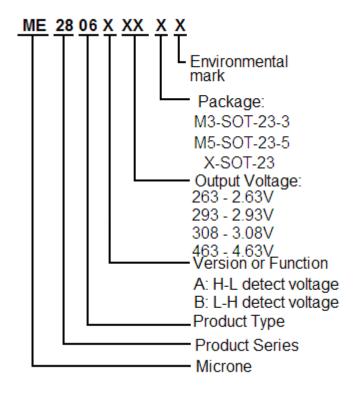


Ultra-small package High-precision Voltage Detector with delay circuit, ME2806 Series

General Description

ME2806 Series is a series of high-precision voltage detectors with a built-in delay time generator of fixed time developed using NMOS process. Internal oscillator and counter timer can delay the release signal without external parts. Detect voltage is extremely accurate with minimal temperature drift. NMOS output configurations are available.

Selection Guide



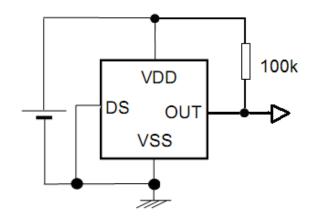
Features

- Highly accuracy: ±2%
- Low power consumption: TYP 0.9uA (V_{DD}=3V)
- Detect voltage range: 1.0V~6.5V in 0.1V increments
- Operating voltage range: 0.7V~7V
- Detect voltage temperature characteristics:
 TYP±100ppm/°C
- Output configuration: NMOS
- Package: SOT-23-3, SOT-23-5, SOT-23

Typical Application

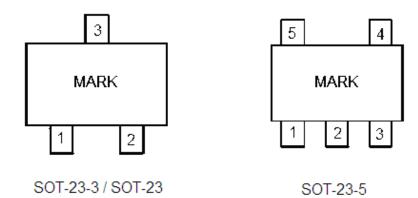
- Power monitor for portable equipment such as notebook computers, digital still cameras, PDA, and cellular phones
- Constant voltage power monitor for cameras, video equipment and communication devices.
- Power monitor for microcomputers and reset for CPUs.
- System battery life and charge voltage monitors

Typical Application Circuit





Pin Configuration

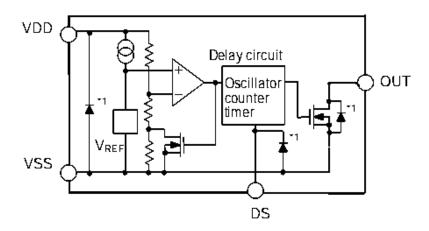


Pin Assignment

PIN Number	Din Nama	Function	
SOT-23-3/SOT-23	Pin Name	Function	
1	VSS	Ground	
2	VOUT	Output Voltage	
3	VDD	Input Voltage	

PIN Number	Din Nome	Frantian	
SOT-23-5	Pin Name	Function	
1	DS	ON/OFF switch for delay time	
2	VSS	Ground	
3	NC	No Connection	
4	VOUT	Output Voltage	
5	VDD	Input Voltage	

Block Diagram



*1. Parasitic diode

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Absolute Maximum Ratings

PARAMETER			SYMBAL	RATINGS	UNITS
V _{DD} Input Voltage		V_{DD}	8	V	
Output Current		I _{OUT}	50	mA	
Output Voltage		NMOS	V _{OUT}	Vss-0.3~ V _{DD} +0.3	V
		SOT-23-3		300	
Continuous Total		SOT-23-5	Pd		mW
Power Dissipation		SOT-23			
Operating Ambient Temperature		T _{Opr}	-40~+85	$^{\circ}$ C	
Storage Temperature		T _{stg}	-40~+125	${\mathbb C}$	
Soldering temperature and time		T _{solder}	260℃, 10s		
ESD		MM	400	V	
		HBM	4000	V	

Electrical Characteristics:

(-V_{DET}(S)=1.0V to 6.5V \pm 2% ,Ta=25 $^{\circ}$ C , unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур	Max.	Units	Test circuit
Detect Voltage	-VDET	-	-VDET (S) ×0.98	-VDET(S)	-VDET(S) ×1.02	٧	1
Hysteresis Range	VHYS	-	0.03	0.06	0.1	٧	
Supply Current1	ISS1	VDD=2V		0.6	1.0	uA	2
	ISS2	VDD=3V (below 2.5V)	-	0.9	1.5	uA 2	
Supply Current2		VDD=5V (2.5V-4.5V)	-	1.4	2.8		2
0 00		VDD=7V (4.5V-6.5V)	-	1.8	3.6		
Output Current	IOUT N-ch	VDS=0.5V VDD=0.7V	0.01	0.16		mA	3
Operating voltage	VDD	-	0.7	-	7	V	1
Td1		VDD=-VDET+1V DS low	32.5	50	72.5	ms	1
Delay time	Td2	VDD=-VDET+1V DS high	25	50	75	us	4
Temperature characteristics	$\frac{\Delta - VDET}{\Delta Ta \bullet - VDET}$	<i>ΔTa</i> =-40°C ~ 85°C	-	±100	±350	ppm/℃	1

Note: 1, -VDET(S): Specified Detection Voltage value

2. -VDET: Actual Detection Voltage value

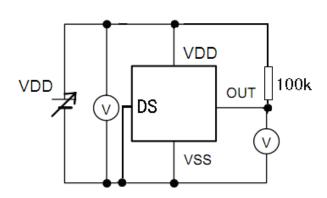
3、Release Voltage: +VDET=-VDET+VHYS

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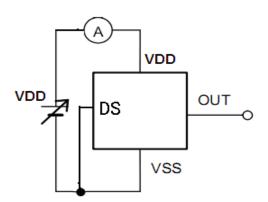


Test Circuits:

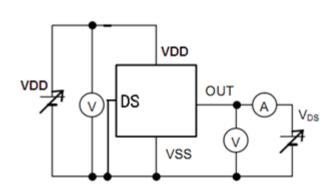
1.



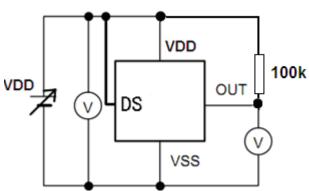
2.



3.



4.





Functional Description:

Basic Operation: NMOS Output (Active Low)

1-1. When the power supply voltage (VDD) is higher than the release voltage (+VDET), the Nch transistor is OFF to provide VDD (high) at the output. Since the Nch transistor N1 in Figure 1 is OFF, the comparator input voltage

$$\operatorname{is} \frac{(R_{\scriptscriptstyle B} + R_{\scriptscriptstyle C}) \bullet VDD}{R_{\scriptscriptstyle A} + R_{\scriptscriptstyle B} + R_{\scriptscriptstyle C}}$$

1-2. When the VDD goes below +VDET, the output provides the VDD level, as long as VDD remains above the detection voltage (-VDET). When the VDD falls below -VDET (point A in Figure 2), the Nch transistor becomes ON, the VSS level appears at the output. At this time the Nch transistor N1 in Figure 1 becomes ON,

$$\frac{R_B \bullet VDD}{R_A + R_B}$$

the comparator input voltage is changed to $R_{\scriptscriptstyle A} + R_{\scriptscriptstyle B}$

- 1-3. When the VDD falls below the minimum operating voltage, the output becomes undefined, or goes to VDD when the output is pulled up to VDD.
- 1-4. The VSS level appears when VDD rises above the minimum operating voltage. The VSS level still appears even when VDD surpasses the -VDET, as long as it does not exceed the release voltage +VDET.
- 1-5. When VDD rises above +VDET (point B in Figure 2), the Nch transistor becomes OFF to provide VDD at the output. The VDD at the OUT pin is delayed for Td due to the delay circuit.

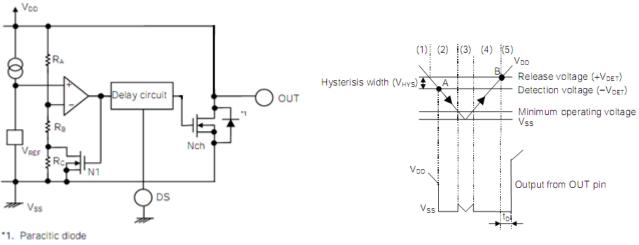


Figure 1 Operation 1

Operation 2 Figure 2

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2. Delay Circuit

2-1. Delay Time

The delay circuit delays the output signal from the time at which the power voltage (VDD) exceeds the release voltage (+VDET) when VDD is turned on. The output signal is not delayed when the VDD goes below the detection voltage (-VDET). (Refer to Figure 2.) The delay time (t_D) is a fixed value that is determined by a built-in oscillation circuit and counter.

2-2. DS Pin (ON/OFF Switch Pin for Delay Time)

The DS pin should be connected to Low or High. When the DS pin is High, the output delay time becomes short since the output signal is taken from the middle of counter circuit (Refer to Figure 3).

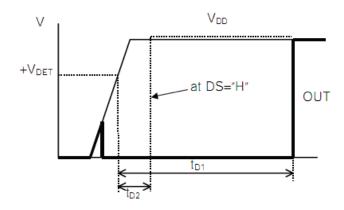


Figure 3

Directions for use:

- 1. Please use this IC within the stated maximum ratings. Operation beyond these limits may cause degrading or permanent damage to the device.
- 2. When a resistor is connected between the V_{DD} pin and the input with NMOS output configurations, oscillation may occur as a result of voltage drops at R_{IN} if load current(I_{OUT}) exists.(refer to the Oscillation Description(1) below)
- 3. When a resistor is connected between the V_{DD} pin and the input with NMOS output configurations, oscillation may occur as a result of through current at the time of voltage release even if load current(I_{OUT}) does not exist. (refer to the Oscillation Description(2) below)
- 4. With a resistor connected between the V_{DD} and the input, detect and release voltage will rise as a result of the IC's supply current—flowing through the V_{DD} pin.
- 5. In order to stabilize the IC's operations, please ensure that V_{DD} pin's input frequency's rise and fall times are more than several u Sec/V.

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Oscillation Description:

1. Output current oscillation with the NMOS output configuration

When the voltage applied at IN rises, release operations commence and the detector's output voltage increase. Load current(I_{OUT}) will flow at R_L . Because a voltage $drop(R_{IN}*I_{OUT})$ is produces at the R_{IN} resistor, located between the input(IN) and the V_{DD} pin. The load current will flow via the IC's pin. The voltage drop will also lead to a fall in the voltage level at the V_{DD} pin. When the V_{DD} pin voltage level falls below the detect voltage level, detect operations will commence. Fllowing detect operations, load current flow will cease and since voltage drop at R_{IN} will disapper, the voltage level at the V_{DD} pin will rise and release operations will begin over again. Oscillation may occur with this "release-detect-release" repetition. Further, this condition will also appear via means of a similar mechanism during detect operations.

2. Oscillation as a result of through current

Since the ME2806 series are NMOS IC's, through current will flow when the IC's internal circuit switching operates(during release and detect operations). Consequently, oscillation is liable to occur as a result of drops in voltage at the through current's resistor (R_{IN}) during release voltage operations.(refer to diagram 2) since hysteresis exists during detect operations, oscillation is unlikely to occur.

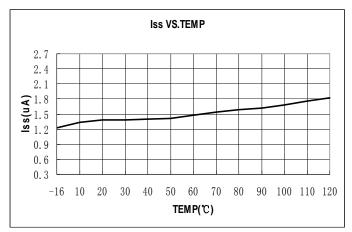
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Type Characteristics

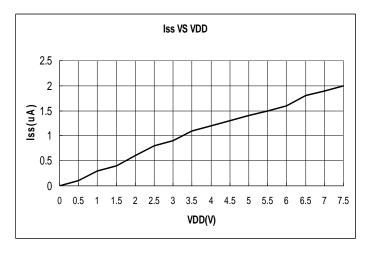
1、SUPPLY CURRENT VS. AMBIENT TEMPERATURE

VDD=5V,-VDET=2.63V

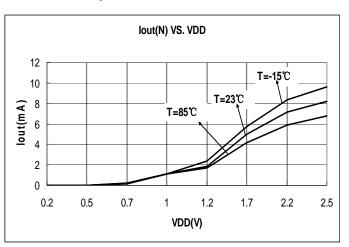


2 SUPPLY CURRENT VS. INPUT VOLTAGE

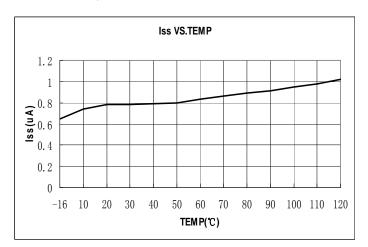
-VDET=2.63V (T=25°C)



4、 OUTPUT CURRENT VS. INPUT VOLTAGE N-ch VDS=0.5V,-VDET=2.63V

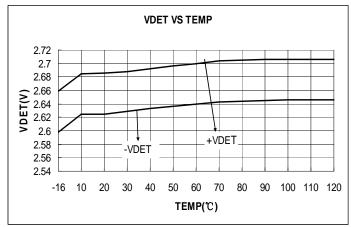


VDD=2.5V,-VDET=2.63V



3 \ DETECT, RELEASE VOLTAGE VS. AMBIENT TEMPERATURE

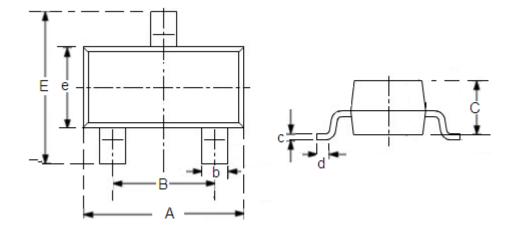
-VDET=2.63V





Package Information

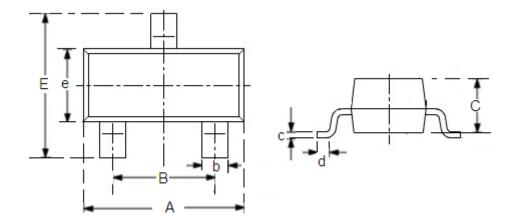
• SOT-23-3



DIM	Millimeters		Inches	
	Min	Max	Min	Max
А	2.7	3.1	0.1063	0.122
В	1.7	2.1	0.0669	0.0827
b	0.35	0.5	0.0138	0.0197
С	1.0	1.2	0.0394	0.0472
С	0.1	0.25	0.0039	0.0098
d	0.2	-	0.0079	-
E	2.6	3.0	0.1023	0.1181
е	1.5	1.8	0.059	0.0708



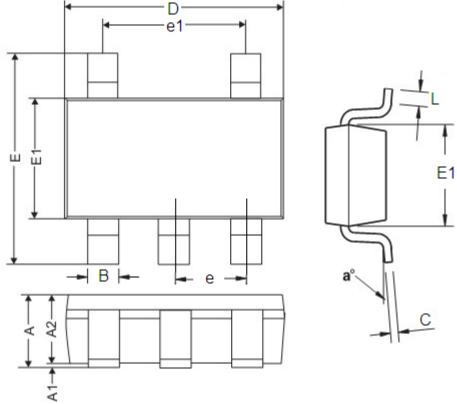
• SOT-23



DIM	Millimeters		Inches	
	Min	Max	Min	Max
А	2.7	3.1	0.1063	0.122
В	1.7	2.1	0.0669	0.0827
b	0.35	0.5	0.0138	0.0197
С	1.0	1.2	0.0394	0.0472
С	0.1	0.25	0.0039	0.0098
d	0.2	-	0.0079	-
E	2.1	2.64	0.0827	0.1039
е	1.2	1.4	0.0472	0.0551



• SOT-23-5



4						
DIM	Millimeters		Inches			
	Min	Max	Min	Max		
А	0.9	1.45	0.0354	0.0570		
A1	0	0.15	0	0.0059		
A2	0.9	1.3	0.0354	0.0511		
В	0.2	0.5	0.0078	0.0196		
С	0.09	0.26	0.0035	0.0102		
D	2.7	3.10	0.1062	0.1220		
E	2.2	3.2	0.0866	0.1181		
E1	1.30	1.80	0.0511	0.0708		
е	0.95REF		0.0374REF			
e1	1.90REF		0.0748REF			
L	0.10	0.60	0.0039	0.0236		
a ⁰	00	30 ⁰	0°	30 ⁰		



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